

# 2N6338, 2N6341

## High-Power NPN Silicon Transistors

... designed for use in industrial–military power amplifier and switching circuit applications.

- High Collector–Emitter Sustaining Voltage –  
 $V_{CEO(sus)} = 100 \text{ Vdc (Min) – 2N6338}$   
 $= 150 \text{ Vdc (Min) – 2N6341}$
- High DC Current Gain –  
 $h_{FE} = 30 - 120 @ I_C = 10 \text{ Adc}$   
 $= 12 \text{ (Min) } @ I_C = 25 \text{ Adc}$
- Low Collector–Emitter Saturation Voltage –  
 $V_{CE(sat)} = 1.0 \text{ Vdc (Max) } @ I_C = 10 \text{ Adc}$
- Fast Switching Times @  $I_C = 10 \text{ Adc}$   
 $t_r = 0.3 \text{ ms (Max)}$   
 $t_s = 1.0 \text{ ms (Max)}$   
 $t_f = 0.25 \text{ ms (Max)}$
- Pb–Free Packages are Available

### \*MAXIMUM RATINGS

Rating	Symbol	2N6338	2N6341	Unit
Collector–Base Voltage	$V_{CB}$	120	180	Vdc
Collector–Emitter Voltage	$V_{CEO}$	100	150	Vdc
Emitter–Base Voltage	$V_{EB}$	6.0		Vdc
Collector Current Continuous Peak	$I_C$	25 50		Adc
Base Current	$I_B$	10		Adc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	200 1.14		W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	$T_J, T_{stg}$	–65 to +200		$^\circ\text{C}$

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$\theta_{JC}$	0.875	$^\circ\text{C/W}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

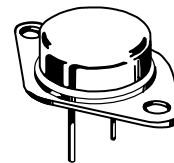
\*Indicates JEDEC Registered Data.



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## 25 AMPERE POWER TRANSISTORS NPN SILICON

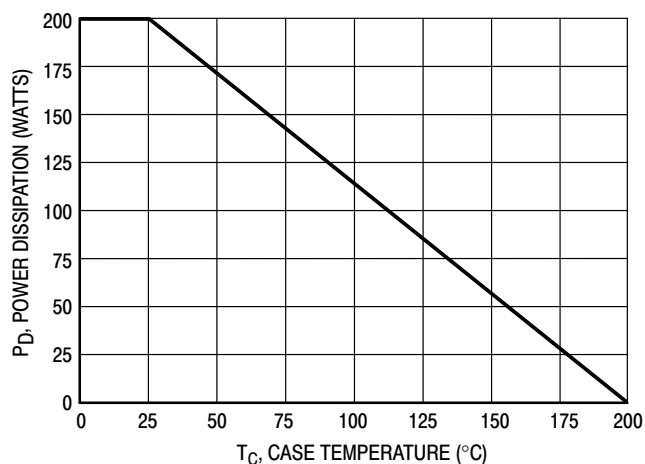


TO–204AA  
CASE 1–07

### ORDERING INFORMATION

Device	Package	Shipping
2N6338	TO–204AA	100 Units / Tray
2N6338G	TO–204AA (Pb–Free)	100 Units / Tray
2N6341	TO–204AA	100 Units / Tray
2N6341G	TO–204AA (Pb–Free)	100 Units / Tray

## 2N6338, 2N6341



**Figure 1. Power Derating**

**\*ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
<b>OFF CHARACTERISTICS</b>					
Collector–Emitter Sustaining Voltage (1) (I <sub>C</sub> = 50 mAdc, I <sub>B</sub> = 0)	2N6338 2N6341	V <sub>CEO(sus)</sub>	100 150	– –	Vdc
Collector Cutoff Current (V <sub>CE</sub> = 50 Vdc, I <sub>B</sub> = 0) (V <sub>CE</sub> = 75 Vdc, I <sub>B</sub> = 0)	2N6338 2N6341	I <sub>CEO</sub>	– –	50 50	μAdc
Collector Cutoff Current (V <sub>CE</sub> = Rated V <sub>CEO</sub> , V <sub>EB(off)</sub> = 1.5 Vdc) (V <sub>CE</sub> = Rated V <sub>CEO</sub> , V <sub>EB(off)</sub> = 1.5 Vdc, T <sub>C</sub> = 150°C)		I <sub>CEx</sub>	– –	10 1.0	μAdc mAdc
Collector Cutoff Current (V <sub>CB</sub> = Rated V <sub>CB</sub> , I <sub>E</sub> = 0)		I <sub>CBO</sub>	–	10	μAdc
Emitter Cutoff Current (V <sub>BE</sub> = 6.0 Vdc, I <sub>C</sub> = 0)		I <sub>EBO</sub>	–	100	μAdc

**ON CHARACTERISTICS (1)**

DC Current Gain (I <sub>C</sub> = 0.5 Adc, V <sub>CE</sub> = 2.0 Vdc) (I <sub>C</sub> = 10 Adc, V <sub>CE</sub> = 2.0 Vdc) (I <sub>C</sub> = 25 Adc, V <sub>CE</sub> = 2.0 Vdc)	h <sub>FE</sub>	50 30 12	– 120 –	–
Collector Emitter Saturation Voltage (I <sub>C</sub> = 10 Adc, I <sub>B</sub> = 1.0 Adc) (I <sub>C</sub> = 25 Adc, I <sub>B</sub> = 2.5 Adc)	V <sub>CE(sat)</sub>	– –	1.0 1.8	Vdc
Base–Emitter Saturation Voltage (I <sub>C</sub> = 10 Adc, I <sub>B</sub> = 1.0 Adc) (I <sub>C</sub> = 25 Adc, I <sub>B</sub> = 2.5 Adc)	V <sub>BE(sat)</sub>	– –	1.8 2.5	Vdc
Base–Emitter On Voltage (I <sub>C</sub> = 10 Adc, V <sub>CE</sub> = 2.0 Vdc)	V <sub>BE(on)</sub>	–	1.8	Vdc

**DYNAMIC CHARACTERISTICS**

Current–Gain – Bandwidth Product (2) (I <sub>C</sub> = 1.0 Adc, V <sub>CE</sub> = 10 Vdc, f <sub>test</sub> = 10 MHz)	f <sub>T</sub>	40	–	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 0.1 MHz)	C <sub>ob</sub>	–	300	pF

**SWITCHING CHARACTERISTICS**

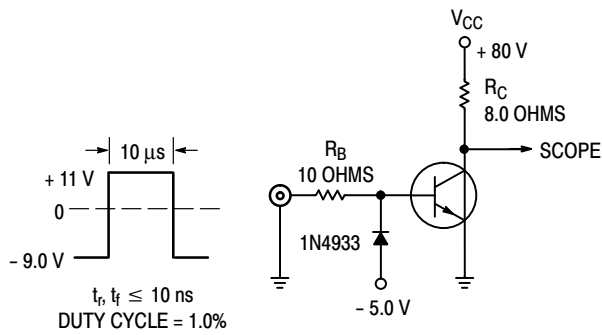
Rise Time (V <sub>CC</sub> ≈ 80 Vdc, I <sub>C</sub> = 10Adc, I <sub>B1</sub> = 1.0 Adc, V <sub>BE(off)</sub> = 6.0 Vdc)	t <sub>r</sub>	–	0.3	μs
Storage Time (V <sub>CC</sub> ≈ 80 Vdc, I <sub>C</sub> = 10 Adc, I <sub>B1</sub> = I <sub>B2</sub> = 1.0 Adc)	t <sub>s</sub>	–	1.0	μs
Fall Time (V <sub>CC</sub> ≈ 80 Vdc, I <sub>C</sub> = 10 Adc, I <sub>B1</sub> = I <sub>B2</sub> = 1.0 Adc)	t <sub>f</sub>	–	0.25	μs

\*Indicates JEDEC Registered Data.

(1) Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

(2) f<sub>T</sub> = |h<sub>fe</sub>| • f<sub>test</sub>.

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NOTE: For information on Figures 3 and 6,  $R_B$  and  $R_C$  were varied to obtain desired test conditions.

Figure 2. Switching Time Test Circuit

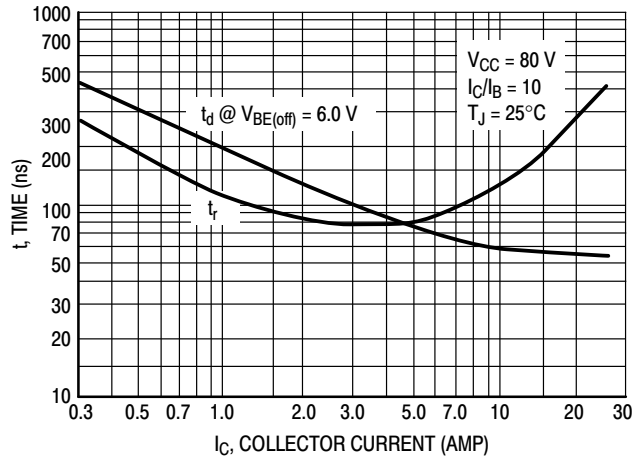


Figure 3. Turn-On Time

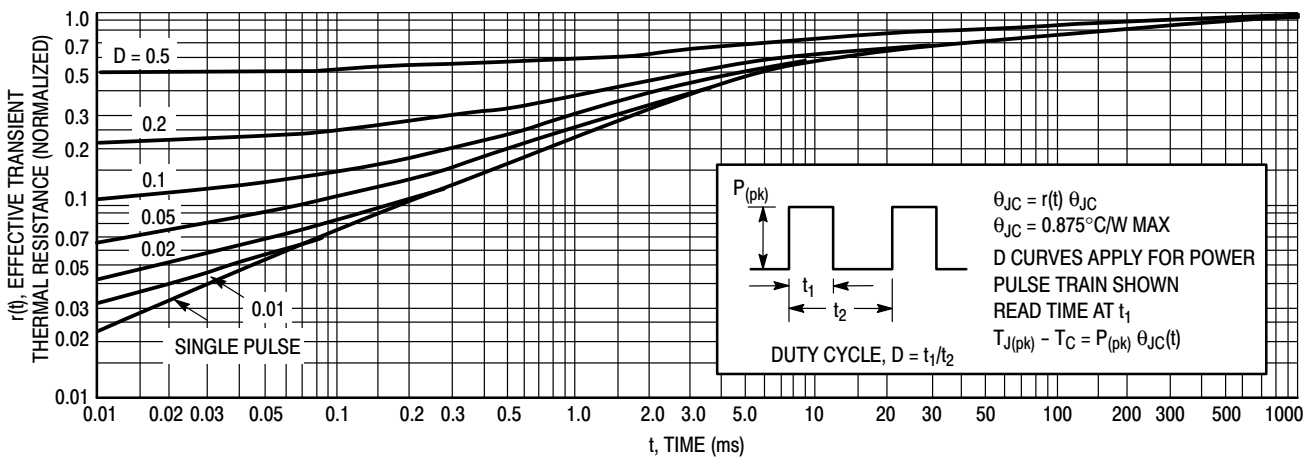


Figure 4. Thermal Response

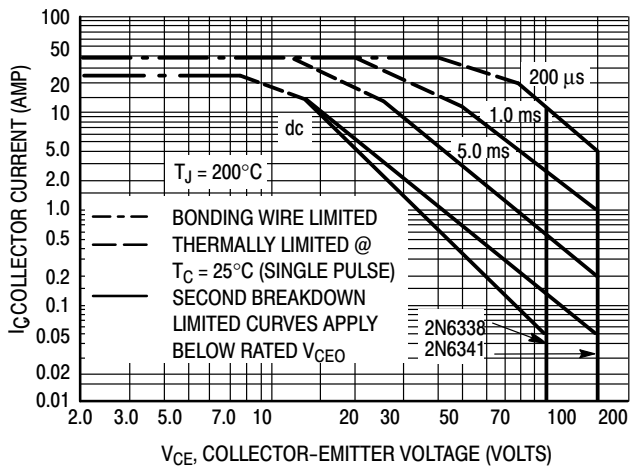


Figure 5. Active Region Safe Operating Area

There are two limitations on the power handling ability of a transistor: average junction temperature and second breakdown. Safe operating area curves indicate  $I_C$ - $V_{CE}$  limits of the transistor that must be observed for reliable operation; i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 5 is based on  $T_{J(pk)} = 200^\circ\text{C}$ ;  $T_C$  is variable depending on conditions. Second breakdown pulse limits are valid for duty cycles to 10% provided  $T_{J(pk)} \leq 200^\circ\text{C}$ .  $T_{J(pk)}$  may be calculated from the data in Figure 4. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

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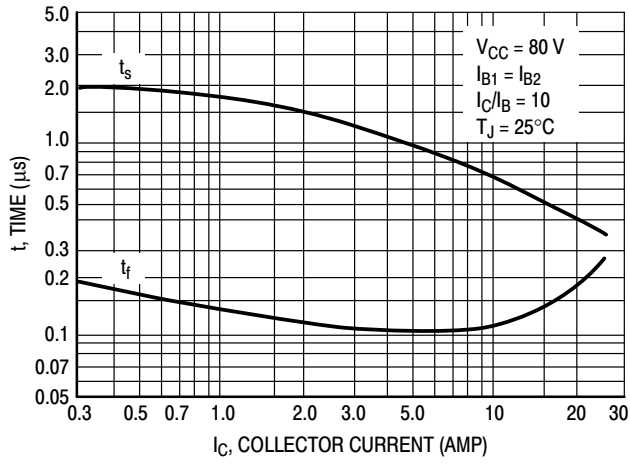


Figure 6. Turn-Off Time

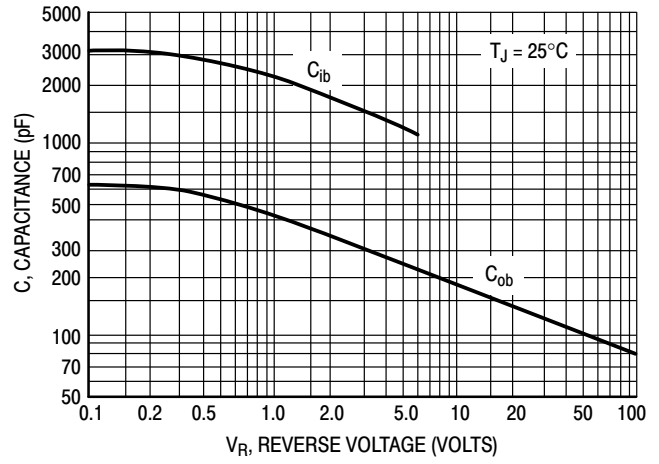


Figure 7. Capacitance

# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



## TO-204 (TO-3) CASE 1-07 ISSUE Z

DATE 05/18/1988



SCALE 1:1



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. ALL RULES AND NOTES ASSOCIATED WITH REFERENCED TO-204AA OUTLINE SHALL APPLY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.550 REF		39.37 REF	
B	---	1.050	---	26.67
C	0.250	0.335	6.35	8.51
D	0.038	0.043	0.97	1.09
E	0.055	0.070	1.40	1.77
G	0.430 BSC		10.92 BSC	
H	0.215 BSC		5.46 BSC	
K	0.440	0.480	11.18	12.19
L	0.665 BSC		16.89 BSC	
N	---	0.830	---	21.08
Q	0.151	0.165	3.84	4.19
U	1.187 BSC		30.15 BSC	
V	0.131	0.188	3.33	4.77

- |  |  |   |   |   |
|--|--|---|---|---|
| <p>STYLE 1:<br/>PIN 1. BASE<br/>2. EMITTER<br/>CASE: COLLECTOR</p> | <p>STYLE 2:<br/>PIN 1. BASE<br/>2. COLLECTOR<br/>CASE: EMITTER</p> | <p>STYLE 3:<br/>PIN 1. GATE<br/>2. SOURCE<br/>CASE: DRAIN</p>           | <p>STYLE 4:<br/>PIN 1. GROUND<br/>2. INPUT<br/>CASE: OUTPUT</p>       | <p>STYLE 5:<br/>PIN 1. CATHODE<br/>2. EXTERNAL TRIP/DELAY<br/>CASE: ANODE</p> |
| <p>STYLE 6:<br/>PIN 1. GATE<br/>2. EMITTER<br/>CASE: COLLECTOR</p> | <p>STYLE 7:<br/>PIN 1. ANODE<br/>2. OPEN<br/>CASE: CATHODE</p>     | <p>STYLE 8:<br/>PIN 1. CATHODE #1<br/>2. CATHODE #2<br/>CASE: ANODE</p> | <p>STYLE 9:<br/>PIN 1. ANODE #1<br/>2. ANODE #2<br/>CASE: CATHODE</p> |   |

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